

SEMI 2141 120NSEC, STATIC, TTL IN/OUT 4096 x 1 N-MOS RAM

FEATURES

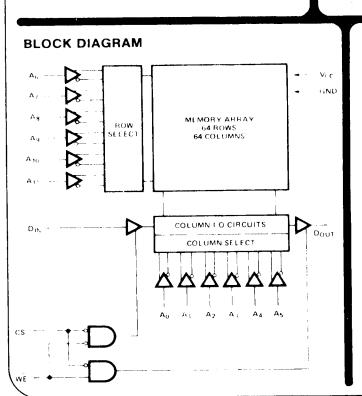
- Industry Standard 2147 Pinout
- Completely Static Memory No Clock or Timing Strobe Required
- Equal Access and Cycle Times
- Single +5V Supply
- Automatic Power-Down
- Directly TTL Compatible All Inputs and Output
- Separate Data Input and Output
- Three-State Output
- Standard 18-Pin Package

GENERAL DESCRIPTION

The EMM SEMI 2141 is a 4096-bit static Random Access Memory organized as 4096 words by 1-bit using N-MOD a high-performance technology. It uses a unique design approach which provides the ease-of-use features associated with non-clocked static memories and the reduced standby power dissipation associated with clocked static memories. To the user this means low standby power dissipation without the need for clocks, address setup and hold times, nor reduced data rates due to cycle times that are longer than access times.

CS controls the power-down feature. In less than a cycle time after CS goes high—deselecting the 2141—the part automatically reduces its power requirements and remains in this low power standby mode as long as CS remains high. This device feature results in system power savings as great as 85% in larger systems, where the majority of devices are deselected.

The 2141 is placed in an 18-pin package configured with the industry standard pinout, the same as the 2147. It is directly TTL compatible in all respects: inputs, outputs, and a single +5V supply. The data is read out nondestructively and has the same polarity as the input data. A data input and a separate three-state output are used.



PIN CONFIGURATION AND LOGIC SYMBOL

PIN CONFIGURATION LOGIC SYMBOL

A ₀ []	1 18	t] voc	1	Λ _C	l
	i i	(**		A1	ı
A1 [.]	2 17	A6		A ₂ A ₃	ı
A ₂	3 16	∐ A,		A.	
A3 []	4 15	□ A _B		A5	l
A4 [21 41	□ Aq		A ₆ Dout	-
		-		A_{j}	l
A ₅	6 13	□ A ₁₀		A ₈	l
Dout [7 12	A11		A g	ı
		F 0.		A ₁₀	ı
WE []	8 11	□ o™		A11	1
GND [9 10	□ cs̄		DIN WE CS	
				7 7 7	•

PIN NAMES

A0-A11	ADDRESS INPUTS	VCC POWER (+5V)
WE	WRITE ENABLE	GND GROUND
ĊS	CHIP SELECT	
DIN	DATA INPUT	
DOUT	DATA OUTPUT	1

TRUTH TABLE

WE	MODE	OUTPUT	POWER
X :	NOT SELECTED	HIGH Z	STANDBY
Ľ	WRITE	HIGH Z	ACTIVE
- й :	READ	DOUT	ACTIVE
	WE X	X NOT SELECTED L WRITE	X NOT SELECTED HIGH Z L WRITE HIGH Z

EMM SEMI, INC.

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EMM SEMI 2141 120NSEC, STATIC, TTL IN/OUT 4096 x 1 N-MOS RAM

	2141-2	2141-3	21414	2141-5	L2141-3	L2141-4	L2141-5
Access/Cycle Time (ns)	120	150	200	250	150	200	250
Operating Current (mA)	70	70	55	55	40	40	40
Standby Current (mA)	20	20	12	12	5	5	5

TYPICAL OUTLINE DRAWING	PACKAGING DIMENSIONS												
		"B" PLASTIC PACKAGE			"A" CERAMIC PACKAGE			GE	"E" CERDIP PACKAGE				
		MILLIMETERS		INCHES		MILLIMETERS		INCHES		MILLIMETERS		INCHES	
	DIM	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
B	Ā	21.590	23 622	0.850	0.930	22 606	.'3 114	0.890	0.910	72.40.	1.400	0.4872	7154
' Ĭ	В	b 096	7 493	0.240	0 295	7 061	7 569	6,278	0.298	-	15.14	-] v_
The same of the second	С		5, 588		0.210		4 826		0 190	-	4 6		1 0 19
- A	ō ·	0.381	0.584	0.015	0 023	0 381	0 584	0.015	0.023	0.50	3584	200	: 0
	E	1 143	1 7 7 8	0.045	0 070	1.016	1 778	0.040	0.070	1 143	3.651	0.041	0.00
the second secon	f	2 286	2 794	0.090	0 110	2.286	2 794	0.090	0 110	150	794	0.090	$_{ m Lat}$
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	н "	0.203	0 305	0.008	0.012	0.203	0.405	0 008	0.012	1 143	0.305	800.0	Ι
	J	7 366	8 255	0.290	0.325	7.620	8 0 7 7	0 300	0.318	2.760	8 128	9.296	9.6
+ HI - HEH - I - K SEATING - K	κ	7.366	10 414	0 290	0.410	620 REF 0 300 REF		REF	8.255	906	0.325	. 5	
PLANE	L	0.508	1.278	0.020	0.050	0 635	1 651	0 025	0 065	0.381	1016	3.315	0.0
	- N	2 540	4 191	0 100	0 165	2 5 4 0	3 810	0 100	0.150	2 - 42	3 37	G (0).	1

WARNING:

MOS CIRCUITS ARE SUBJECT TO DAMAGE FROM STATIC DISCHARGE

Internal static discharge circuits are provided to minimize part damage due to environmental static electrical charge build upa. Industry established recommen dations for handling MOS circuits include.

- Ship and store product in conductive shipping tubes or in conductive loam plastic. Never ship or store product in non-conductive plastic containers or non-conductive plastic foam material.
- 2. Handle MOS parts only at conductive work stations
- 3 Ground all assembly and repair tools

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EMM SEMI reserves the right to make changes at any time in order to improve design and to supply the best product possible.

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